

# Irradiated structures & LGAD doping profile measurements

NinN test production, TCTs and SIMS on LGAD test structures

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# Overview



Introduction

## Reminders

Doping profile Project overview and irradiations

SiMS on irradiated structures

## Measurements and comparison

Calibration and rescaling to unirradiated profiles

LGAD Doping profiles

## Measurements on CNM test structures

Initial results and comparisons

Gallium LGAD  
Run profiles

## Preliminary doping profiles

Measurements and through oxide tests

TCT  
Measurements

## CiS NinN irradiated diodes

Initial results and cartography

Concluion

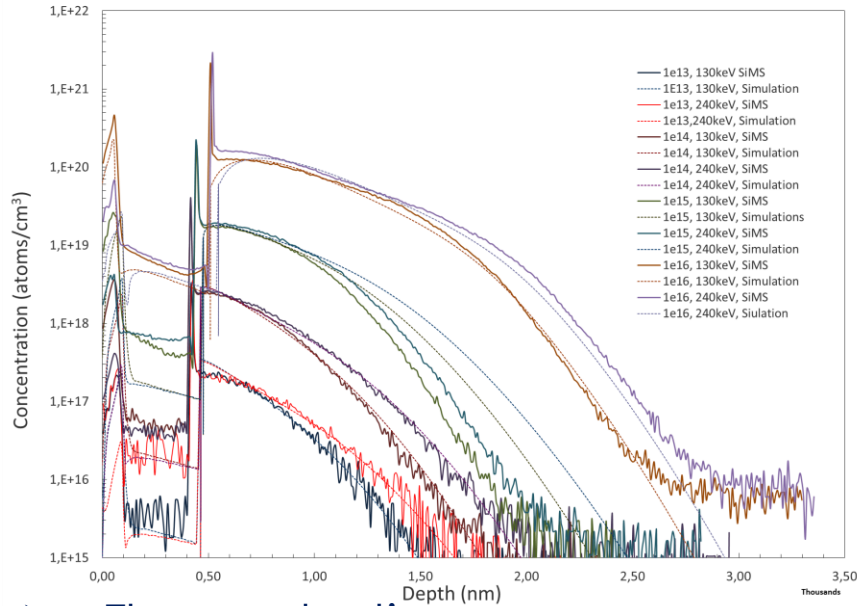
## Conclusions and plans

Further investigations and simulations

# Reminders

## Doping profiles study and irradiations

ADVACAM 2Ωhm\*cm, 100nm Screen Oxide, Non-etched

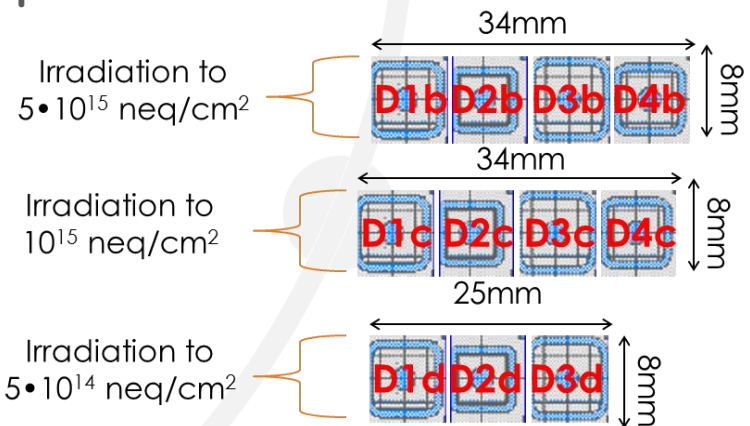


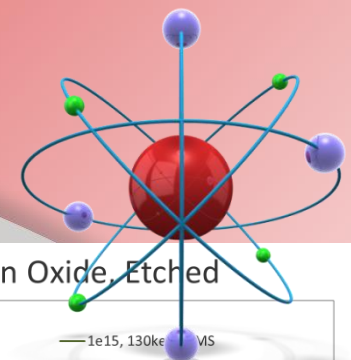
### Irradiations

- ❖ Several SiMS samples were irradiated at KIT
- ❖ Fluences  $10e16 n_{eq}/cm^2$  with 20GeV protons
- ❖ Different Guard rings design diodes also include irradiated to fluences form  $5e10^{14}$  to  $10e^{16} n_{eq}/cm^2$
- ❖ SiMS and TCT measurements preformed

### The production

- ❖ Several wafers ordered of controlled parameters
- ❖ Measured and simulated
- ❖ Goal to calibrate simulations, to develop measurement techniques and understand basic processes



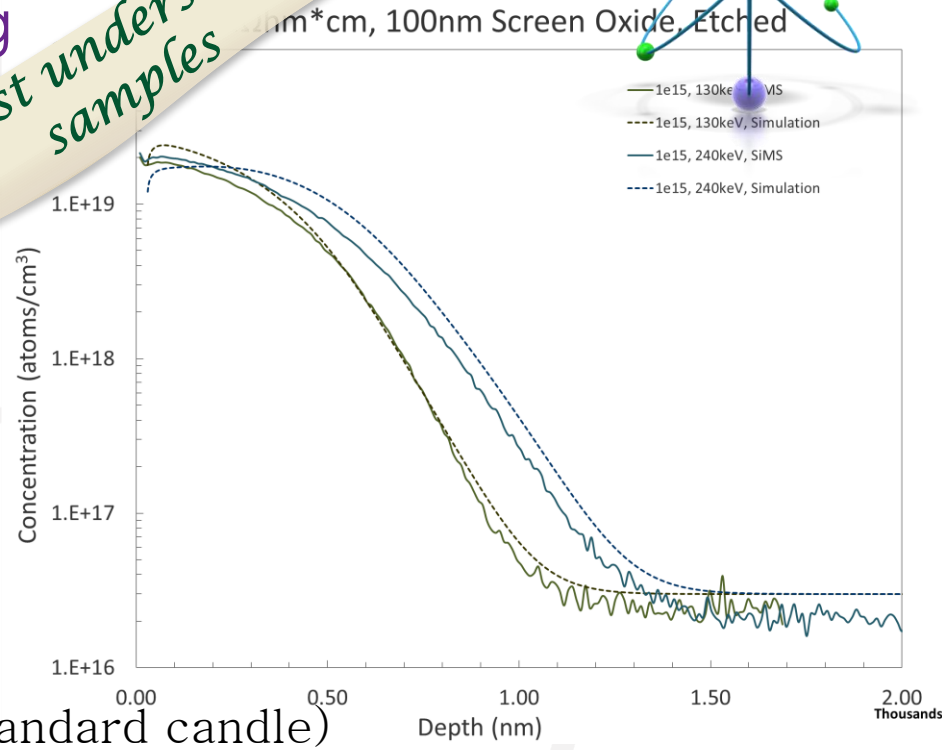


# •Irradiated SiMS

## Measurements and rescaling

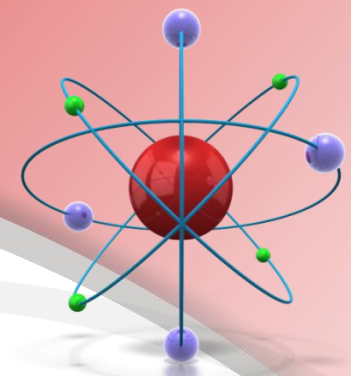
*Most understood samples*

1. Not expecting any SiMS profile alteration after irradiation in principle
2. Perhaps slight changes due to point annealing if not sufficiently cooled
3. Possibility of sputtering but irradiation dose was moderate for this effect



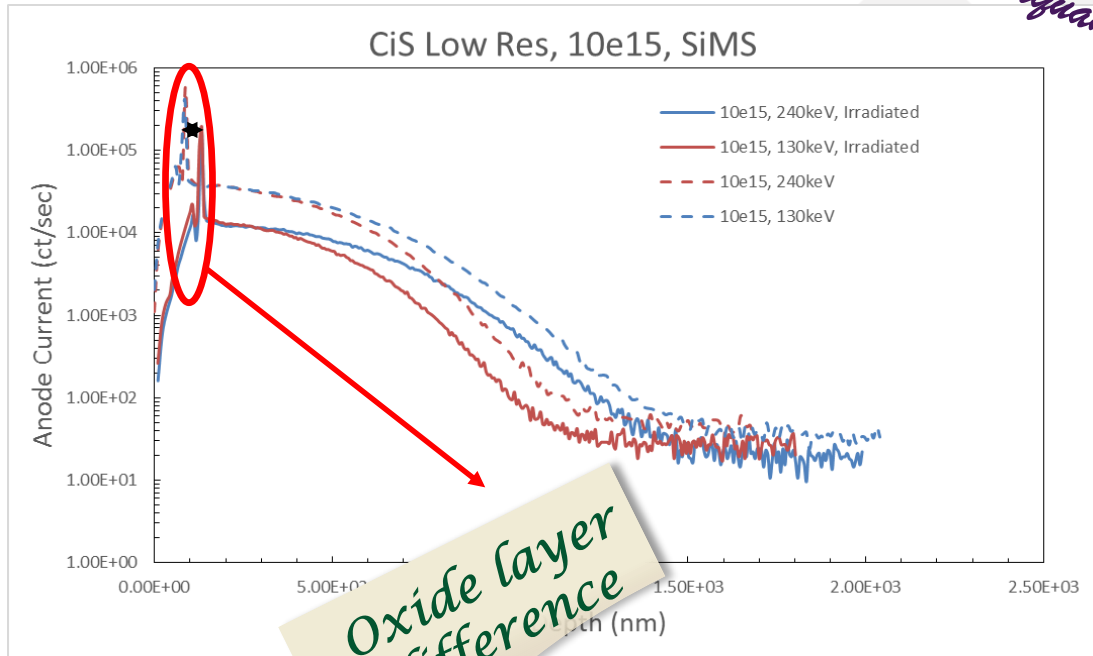
The sample:

- $10^{15}\text{cm}^{-2}$  at 130 and 240 keV (standard candle)
- 100nm layer of oxide
- Good agreement between simulation and SiMS measurements
- Irradiated to  $10^{16}n_{\text{eq}}$  at KIT but received room temperature annealing
- Cannot be used to perform SRP in order to investigate dopant displacement and changes in electrical characteristics.



# •Irradiated SiMS

## The measurements



Oxide layer difference

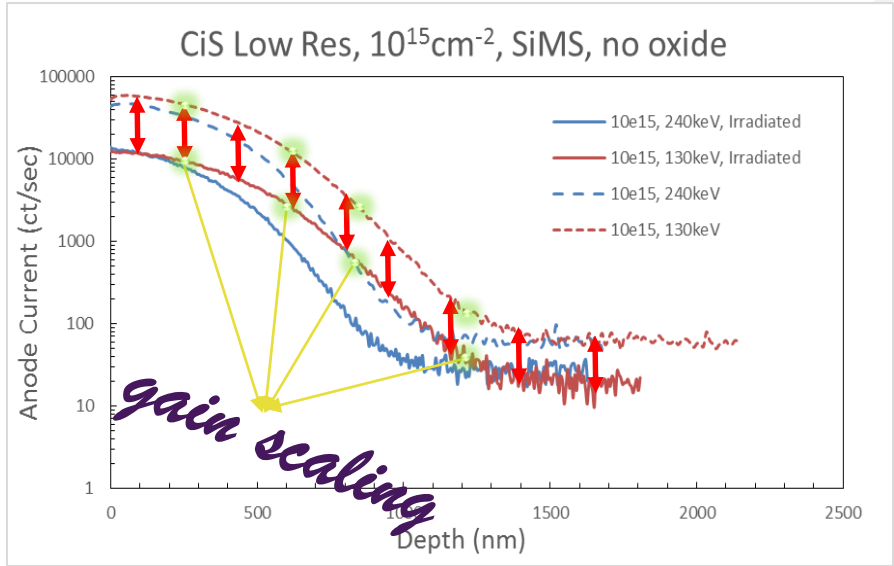
*Unquantified SiMS data*

- Quantification of measurements
  - ❖ The results were not quantified
  - ❖ Comparison is performed with unirradiated sample data
  - ❖ Different calibration parameters were used.

- Take into account different penetrations rates in different regions
- Correct for gain differences
- Scale to silicon level only

# •Irradiated SiMS

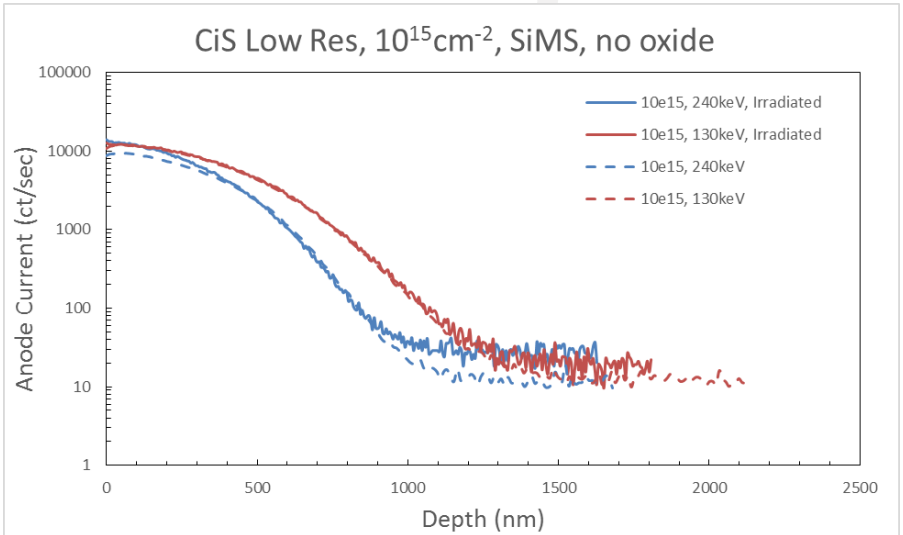
## Scaling



**Conclusion:** No alteration to the doping profile distribution for the two samples is observed after all corrections!

### ➤ Quantification of measurements

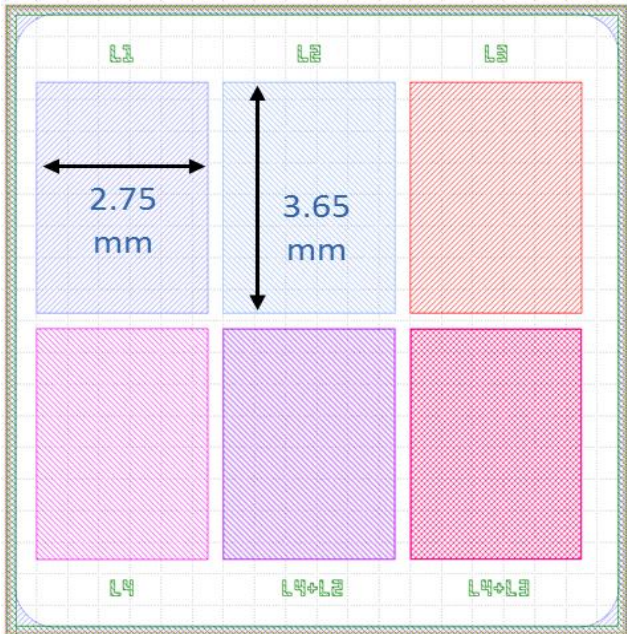
- ❖ To accommodate for the ion beam penetration difference, comparison performed only in silicon region
- ❖ Gain difference is calculated in several regions and corrected for.



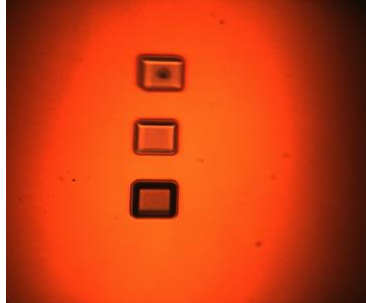
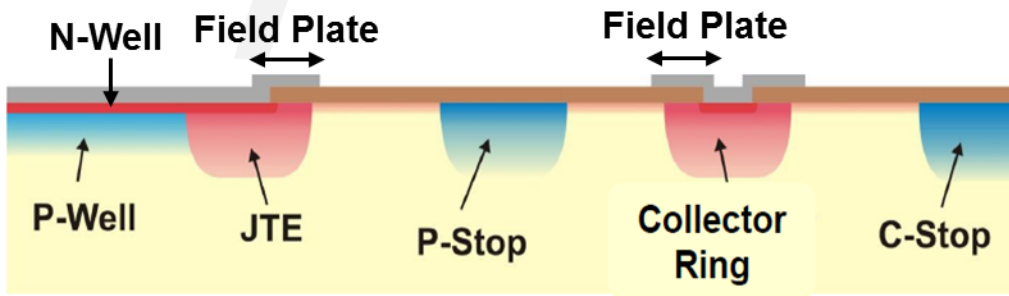


# •LGAD Doping profiles

## The structure

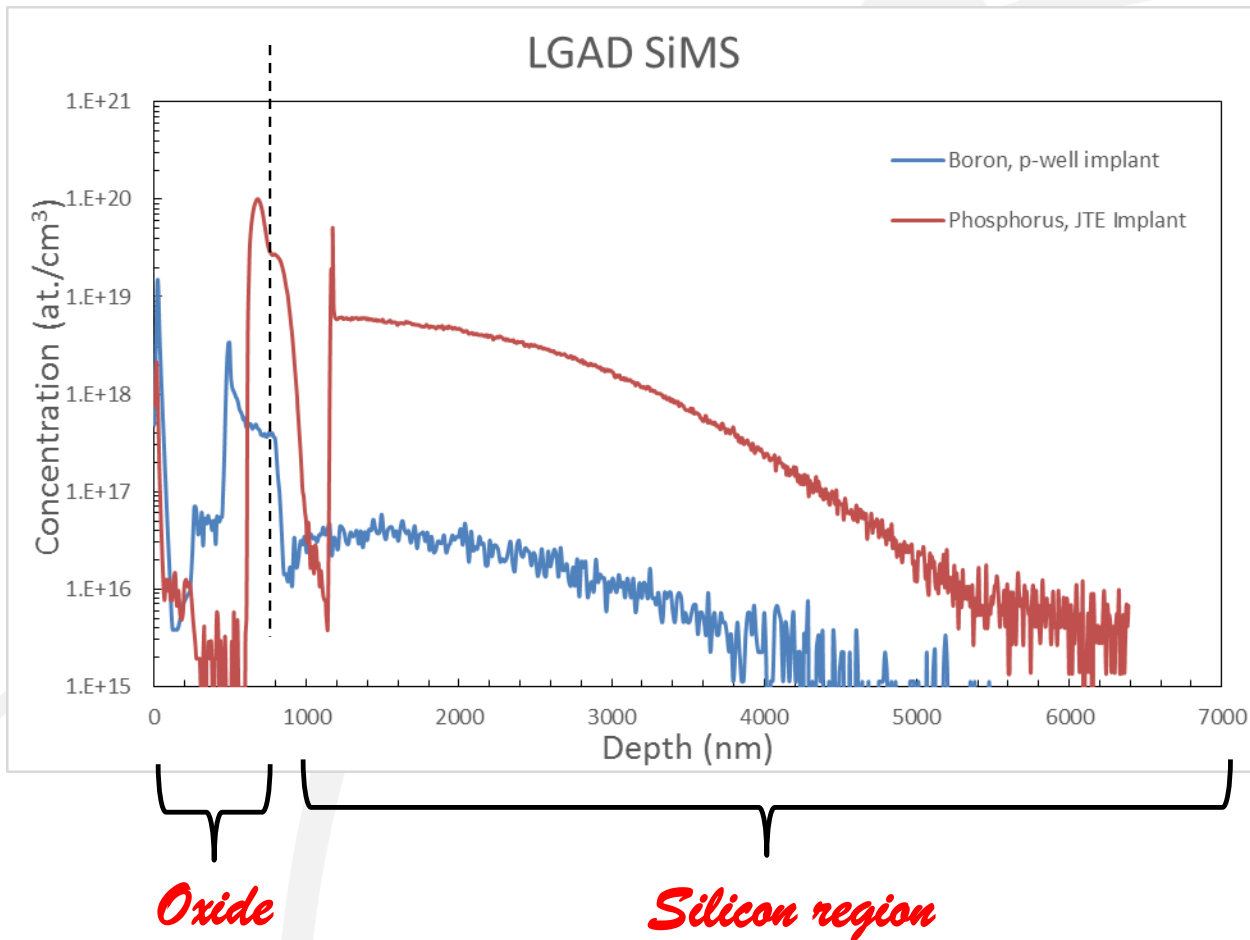


1. Jointly designed mask with CNM to accommodate for SiMS limitations
2. 6 individual regions:
  - L1 P-Stop, C-Stop Well
  - L2 P-Well (P Multiplication)
  - L3 JTE
  - L4 N-Well
  - L4 + L2 N-Well over P-Well
  - L4 + L3 N-Well over JTE
3. September Run that was delivered in February



# •LGAD Doping profiles

## P-Well and JTE

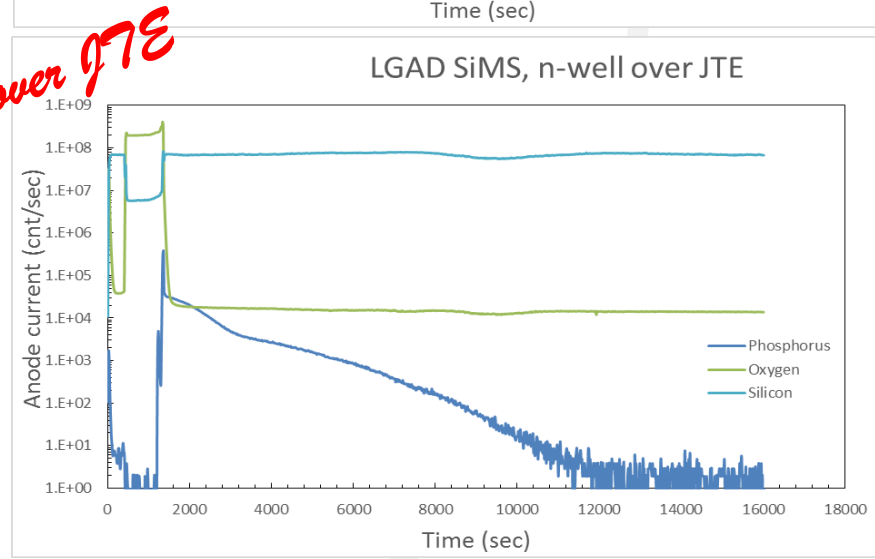
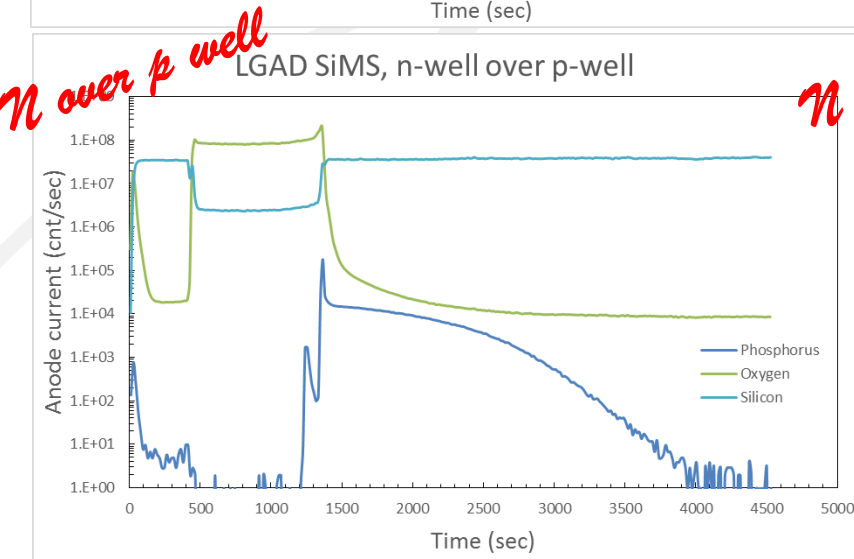
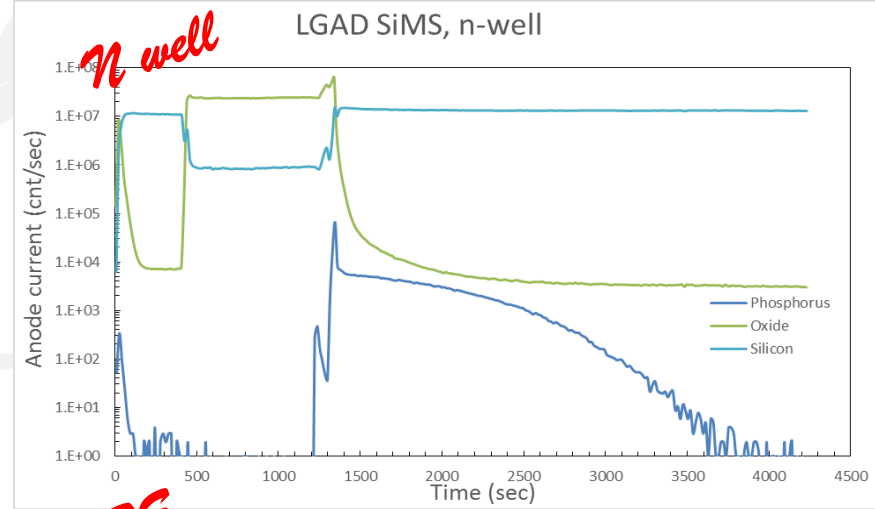
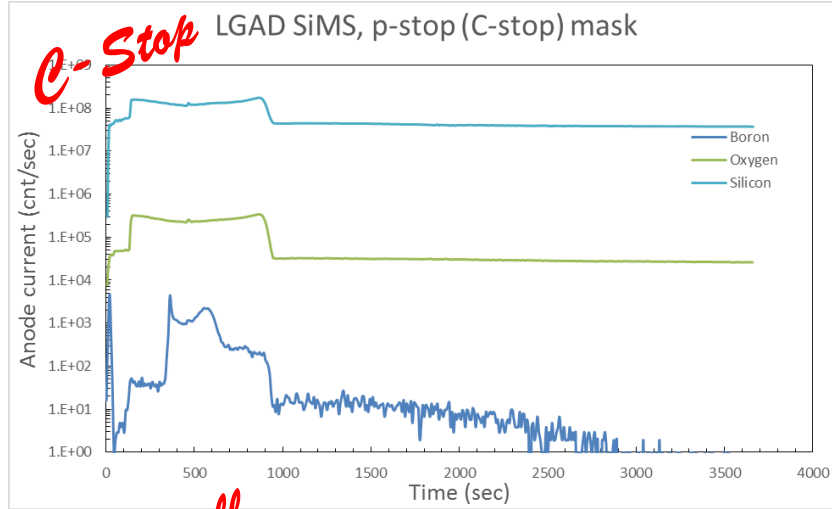


- 4 different layers were taken into account for each profile
- Maximum depth of 6 $\mu$ m to avoid inconsistencies due to crater roughness
- Completely quantified results for the p-well boron implant and the phosphorus JTE implantation.



# •LGAD Doping profiles

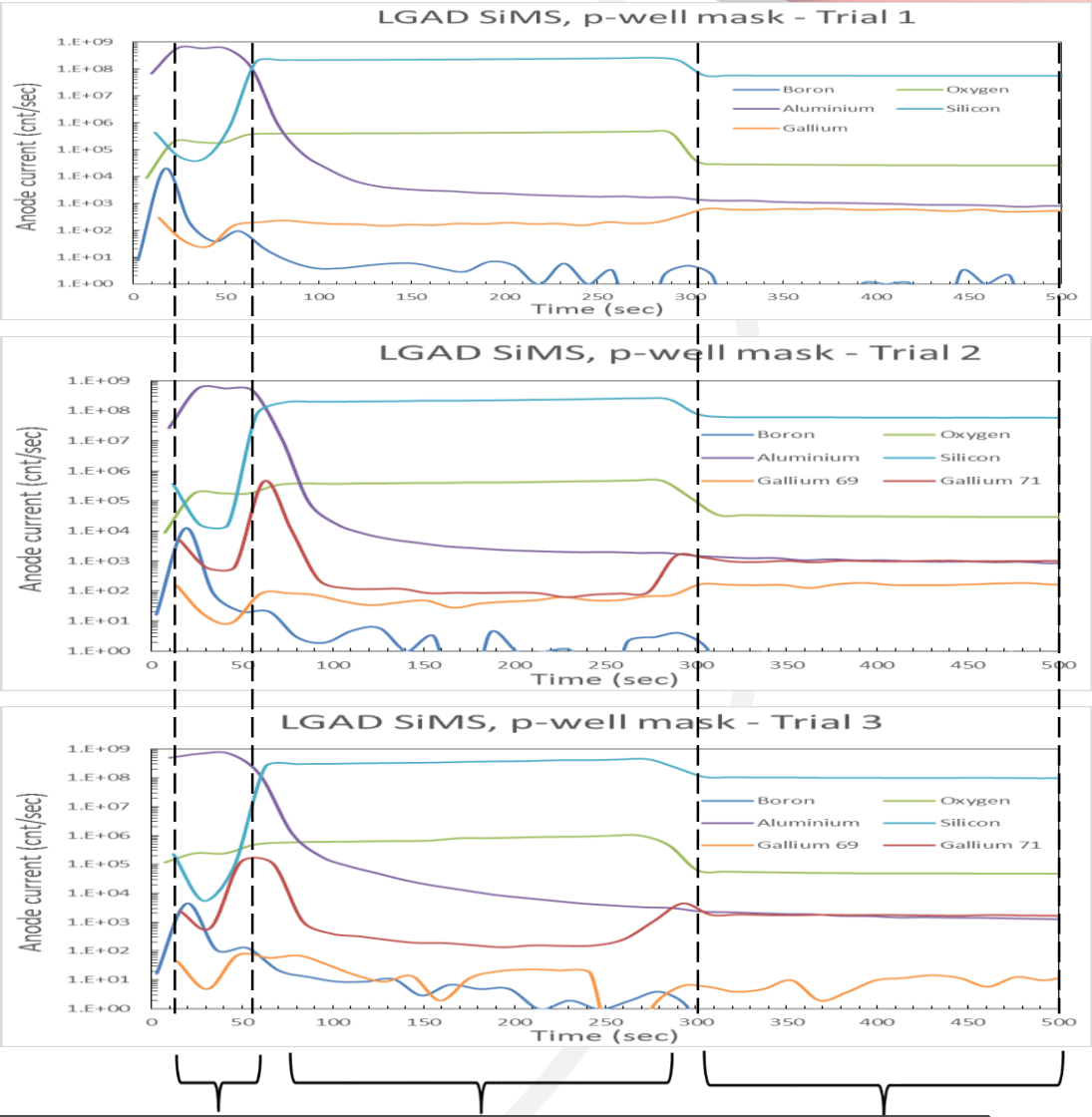
## Non quantified measurements



# •LGAD Doping profiles

## The Gallium case

- ✓ A separate set of wafers were measured where the p-well was replaced by gallium
- ✓ We noticed very low concentrations of Gallium 69 and higher of Ga71
- ✓ Non quantified measurements yet
- ✓ All implant seems to be trapped within the oxide region and none is present at the substrate
- ✓ Simplest case measures with one implantation

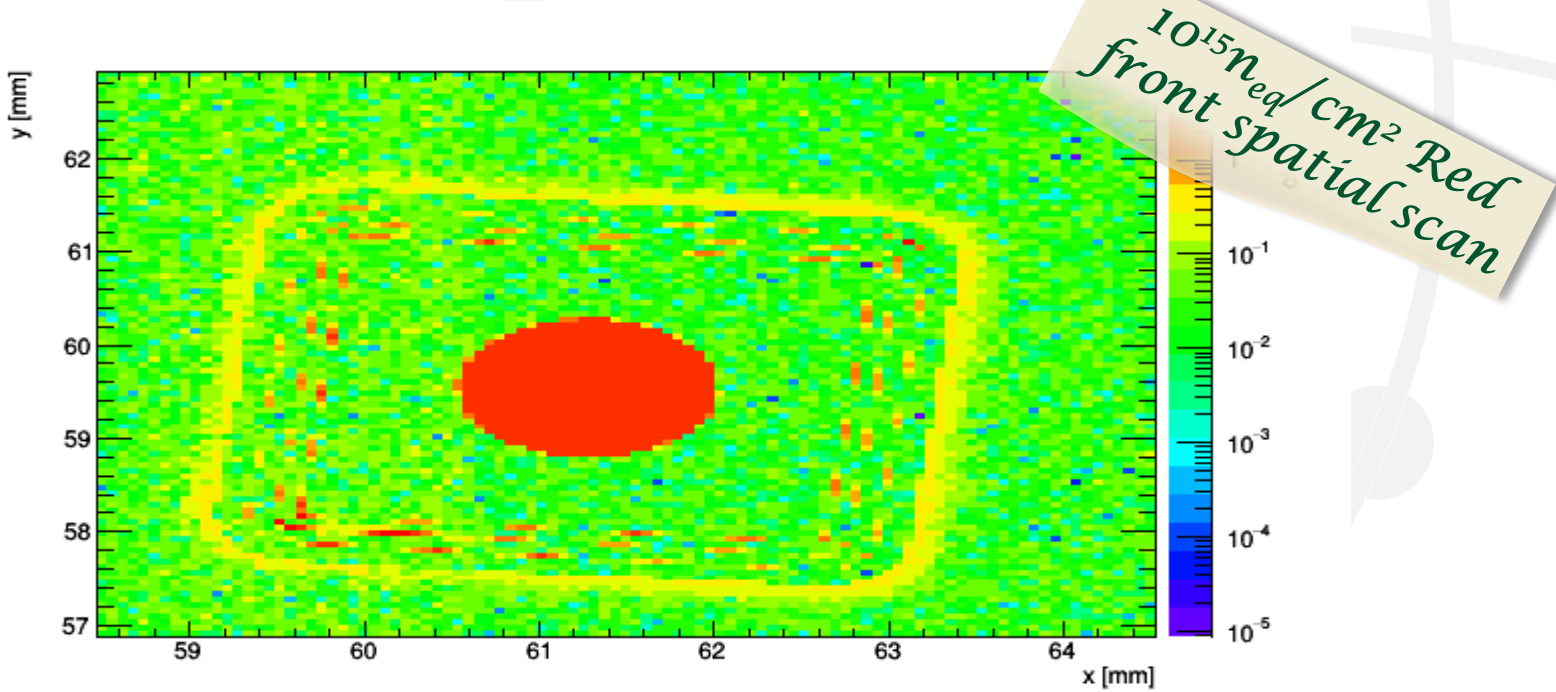


*Special thanks to Christian Galbraith  
For using is setup*

# •TCT measurements

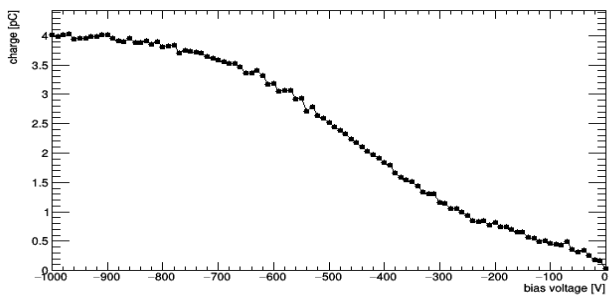
## CiS irradiated Diodes

- ✓ 4Well over inversion fluency
- ✓ different fluencies used, form  $5 \cdot 10^{14}$  to  $1 \cdot 10^{16}$  irradiated at KIT
- ✓ All samples were completely functional at -15C
- ✓ Used front and back red as well as front IR technique
- ✓ Detailed cartography for the intermediate fluency



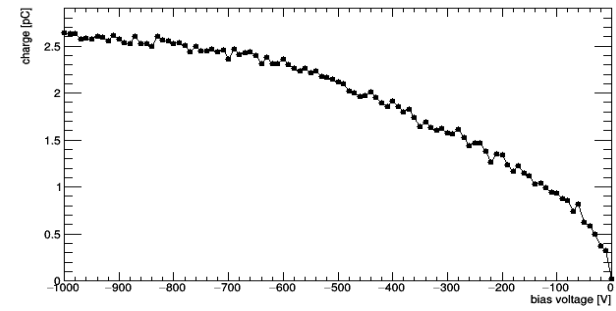
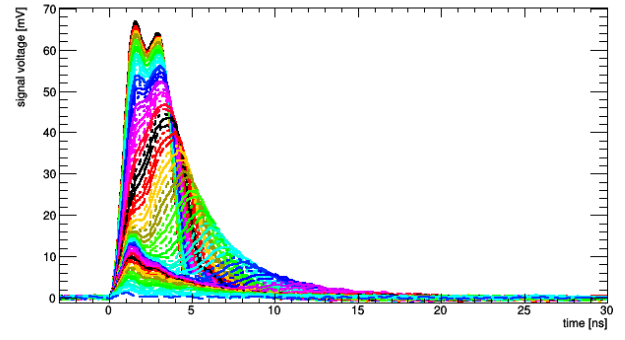
# •TCT measurements

3 GR Diode at  $5 \cdot 10^{14} n_{eq}/cm^2$

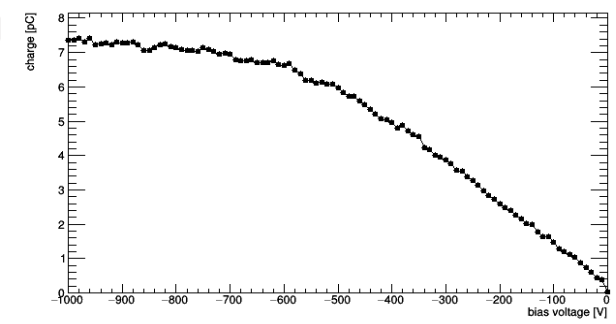
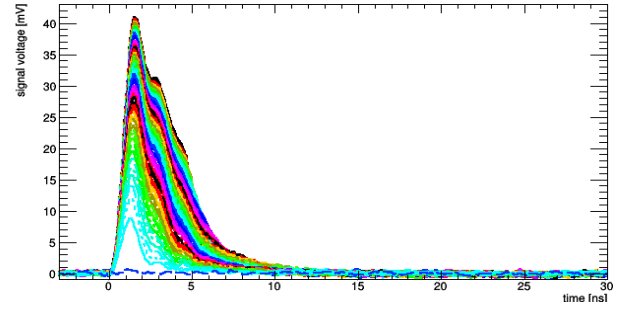


Charge collection and signal response for the three cases:

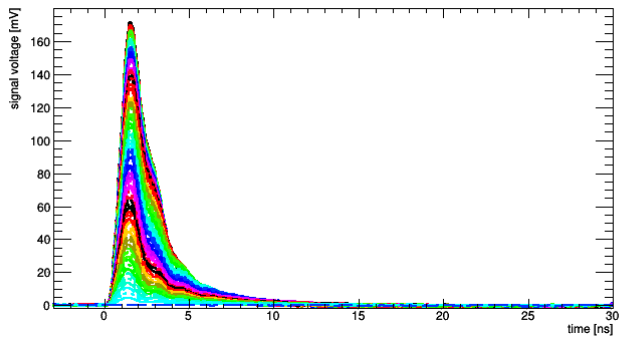
**Red Front**



**Red back**



**Infrared Front**



# •Future Plans - Conclusions

## SiMS –SRP – LGADs - TCT

- ❑ For the irradiated doping profiles no change is observed before and after irradiation with respect to SiMS measurements
- ❑ Preliminary measurements in the standard LGAD production with boron seem to be well with reasonable limits, quantification has to be completed.
- ❑ Gallium substitution of the boron implantation present issues that have yet to be understood.
- ❑ Using the TCT measurements of the different irradiation fluencies we expect to accurately calibrate the simulator to compensate for radiation damage effects

**THANK YOU FOR YOUR  
ATTENTION!!**